Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model **[List multiple models if applicable.]**
HP Advanced Services v2 zl Module w/ HDD (J9857A)
HP Advanced Services v2 zl Module w/ SSD (J9858A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

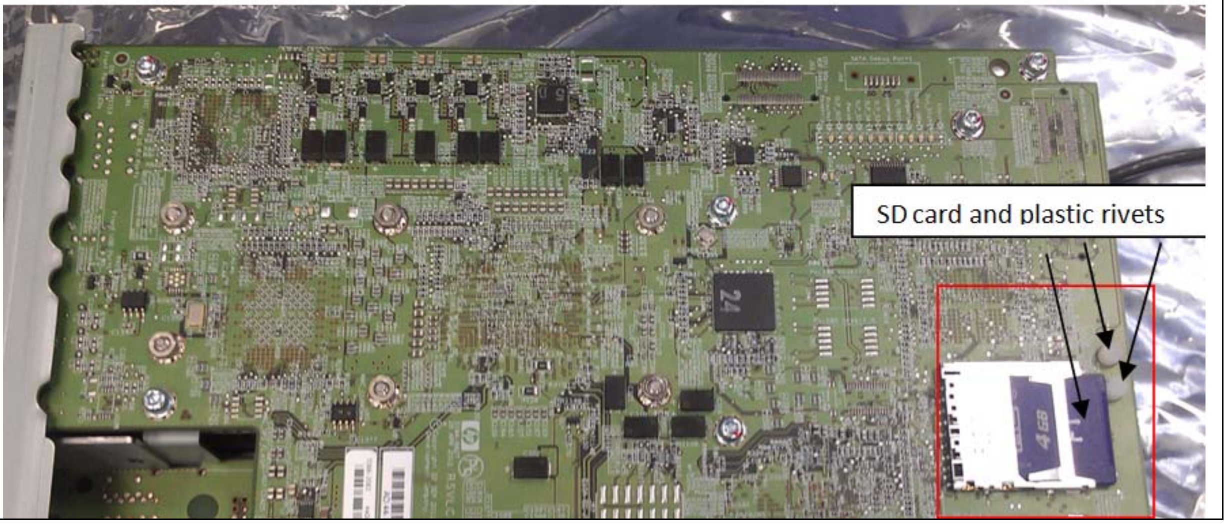
Tool Description	Tool Size (if applicable)
Torx Screw Drivers	T-8, T-10
Phillips Screw Driver	P1
Hex wrench or nut drivers for M3 Hex nut	

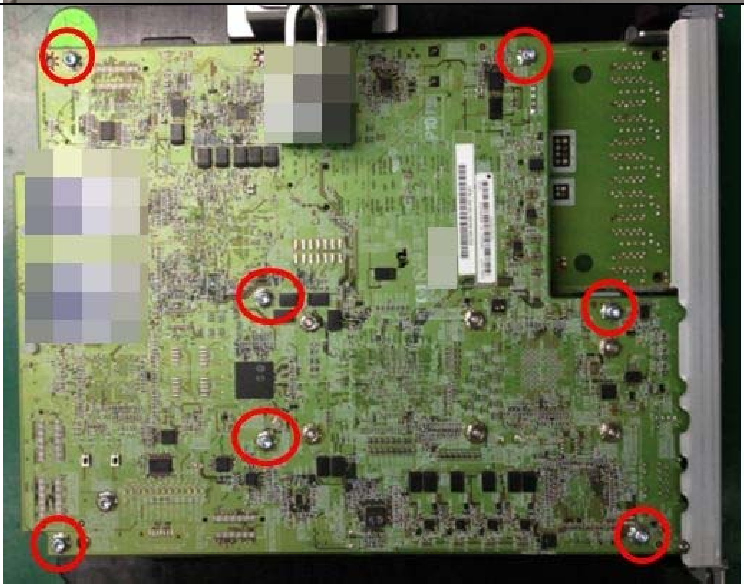
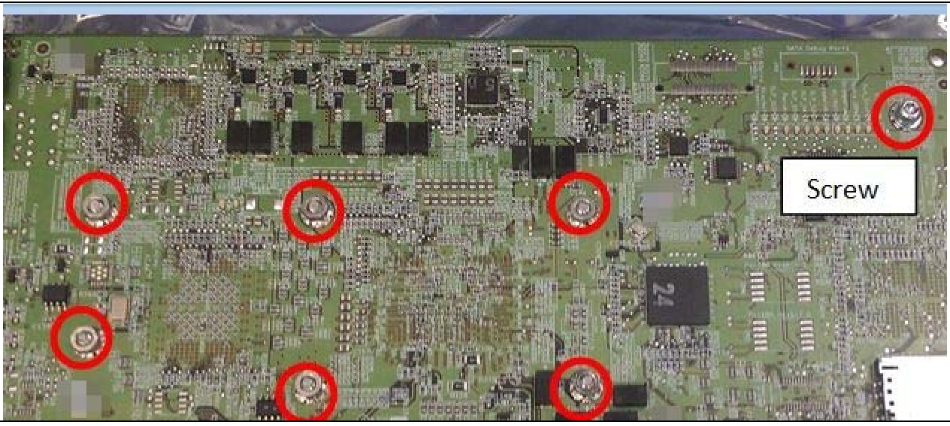
3.0 Product Disassembly Process

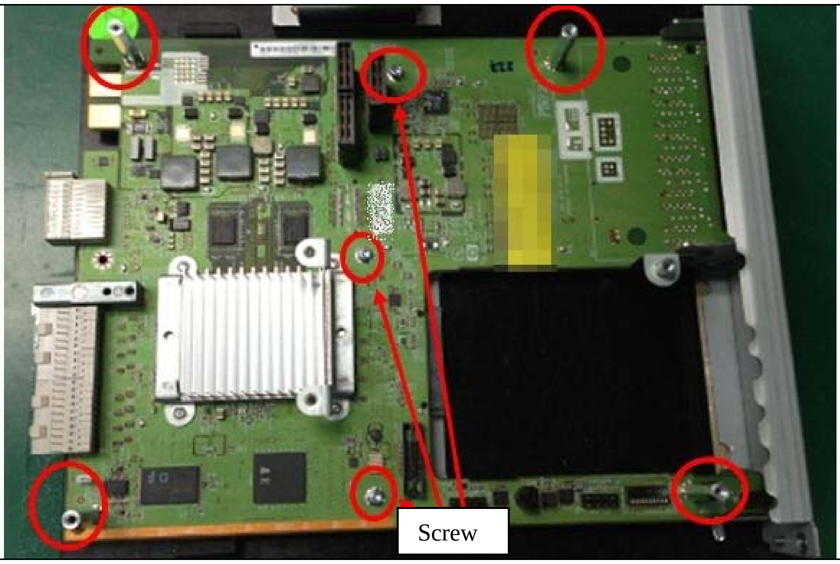
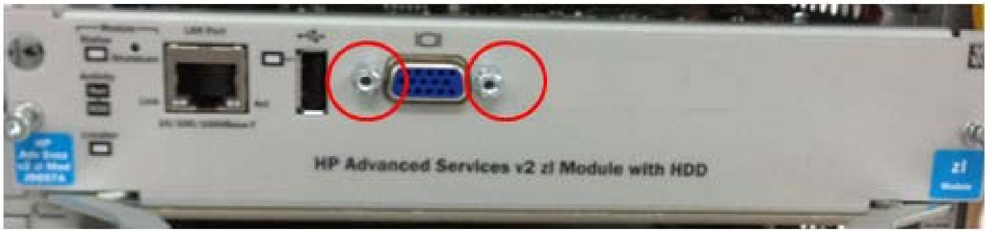
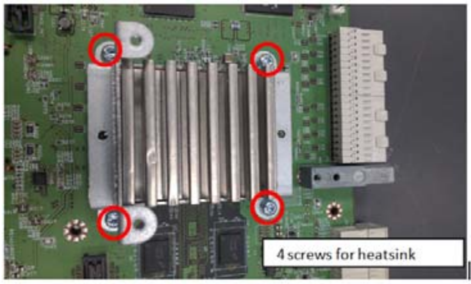
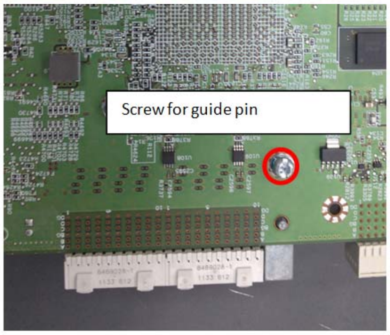
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove the plastic rivets and the SD card on the top PCA. Refer to Pic 1
2. Using the Phillips screw driver, remove the 4 Phillips screw attaching the hard drive to the PCA. Follow the removal instruction on the replacement label. Refer to Pic 2
3. Remove the top PCA by removing the 7 screws using the T-10 screwdriver. Refer to Pic 3.
4. After removing the top PCA, on the top PCA,
    1. Remove the heatsink by removing the 6 hex nuts (using a hex wrench or nut driver) and 1 screw (using the T-10 screwdriver), refer to pic 4
    2. Remove the DIMM module and the cell battery
5. On the bottom PCA, remove the 3 Torx screws (using a T-10 screwdriver) and the 4 standoffs using a boxtype Torx screwdriver. Refer to Pic 5
6. To remove the bottom PCA, remove the screw lock kit on the front of the bulkhead. Refer to pic 6
7. After removing the bottom PCA, on the bottom PCA, refer to pic 7,
    1. Remove the heatsink by removing the 4 Torx screws (using a T-10 screwdriver)
    2. Remove the guide pin by using a T-10 Torx screwdriver to remove the 1 screw that attached the guide pin to the PCA
8. Remove the 2 screws and springs on the bulkhead. Refer to pic 8

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Pic	Illustration
1	

2	 Serial No. SG30GD8053 Media Installation Media Removal Replace with HP Spare
3	
4	 Screw

5	Screw
6	HP Advanced Services v2 zl Module with HDD zl
7	4 screws for heatsink Screw for guide pin
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